

HT78XX Series 500mA TinyPower[™] LDO

Features

- Output voltage ranges: Fixed range of 1.8V, 2.5V, 2.7V, 3.0V, 3.3V, 5.0V type.
- Highly accuracy: ±2%
- Low voltage drop: 360mV (typ.), V_{OUT}=5.0V at 500mA
- Guaranteed output current: 500mA

- Low quiescent current: 5μA (typ.)
- · Current limiting
- Over-temperature shutdown
- SOT-89, TO-92 Packages

Applications

- · Battery powered systems
- · Personal Digital Assistants
- · Peripheral cards

- PCMCIA cards
- · Personal Communication Equipment

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General Description

The HT78XX series of positive, linear regulators features low quiescent current ($5\mu A$ typ.) with low dropout voltage, making them ideal for battery applications. The devices are capable of supplying 500mA of output current continuously.

They are available with several fixed output voltages ranging from 1.8V to 5.0V. Although designed primarily

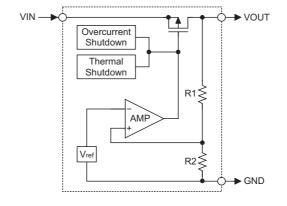
as fixed voltage regulators, these devices can be used with external components to obtain variable voltages and currents.

These rugged devices have Thermal Shutdown and Current Limiting to prevent device failure under the "Worst" of operating conditions.

Selection Table

Part No.	Output Voltage	Tolerance	Package
HT7818	1.8V		
HT7825	2.5V		
HT7827	2.7V	.00/	SOT-89 TO-92
HT7830	3.0V	±2%	
HT7833	3.3V		
HT7850	5.0V		

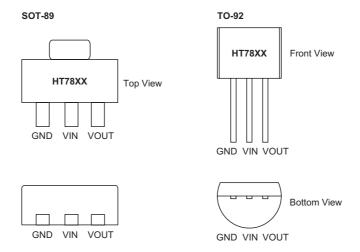
Block Diagram



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Pin Assignment



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Note: For lead free devices, a # mark is suffixed at the end of the date code.

Absolute Maximum Ratings*

Maximum Supply Voltage up to 8.5V	Storage Temperature
Operating Temperature40°C to 85°C	

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Thermal Information

Symbol	Parameter	Package	Max.	Unit
0	Thermal Resistance (Junction to Ambient)	SOT-89	200	°C/W
θJA	θ _{JA} (Assume no ambient airflow, no heat sink)	TO-92	200	°C/W
P _D Power Dissipation	Dawar Dissination	SOT-89	0.50	W
	Power Dissipation	TO-92	0.50	W

Note: P_D is measured at Ta= 25°C

[&]quot;*" Absolute maximum ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. The guaranteed specifications apply only for the test conditions listed.



Electrical Characteristics

 T_j =25°C, V_{IN} = V_{OUT} +1.0V, I_O =1mA, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{IN}	Input Voltage	_				8	V
ΔV_{OUT}	Output Voltage Tolerance	_		-2		2	%
I _{SS}	Quiescent Current	I _O =0mA		_	5	7	μА
ΔV_{LOAD}	Load Regulation (Note1)	1mA≤l _{OUT} ≤500mA		_	0.004	0.008	%/mA
			V _O ≤1.8V	_	800	1200	
V _{DROP}	V _{DROP} Dropout Voltage (Note2)	ΔV _{OUT} =2% I _{OUT} =500mA	2.5V≤V _O ≤2.7V	_	500	650	mV
			3.0V≤V _O ≤5.0V	_	360	500	
ΔV_{LINE}	Line Regulation	V _{OUT} +1.0V≤V _{IN} ≤8.0V		_	0.2	0.3	%/V
I _{LIM}	Current Limit (Note3)	ΔV _{OUT} =10%		500	_	_	mA
<u>Δ</u> V _{OUT} ΔT _a	Temperature Coefficient	-40°C <ta<85°c< td=""><td>_</td><td>±0.8</td><td>_</td><td>mV/°C</td></ta<85°c<>		_	±0.8	_	mV/°C

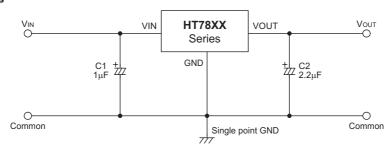
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Note:

- 1. Load regulation is measured at a constant junction temperature, using pulse testing with a low ON time and is guaranteed up to the maximum power dissipation. Power dissipation is determined by the input/output differential voltage and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range. The maximum allowable power dissipation at any ambient temperature is $P_D = \left(T_{J(MAX)} T_a\right) / \theta_{JA}.$
- Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at V_{IN} = V_{OUT}+1V with a fixed load.
- 3. Current limit is measured by pulsing for a short time.

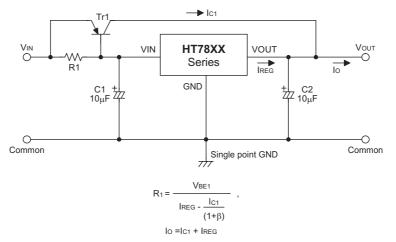
Application Circuits

Basic Circuits



Typical Application Circuits

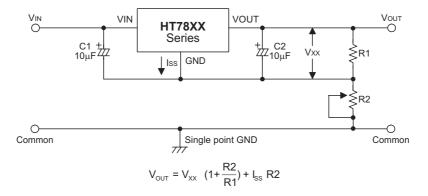
· High output current positive voltage regulator



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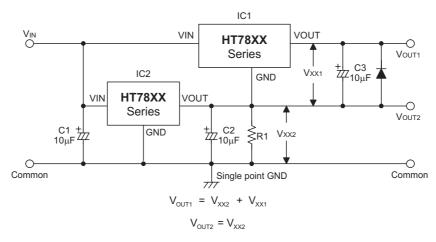


• Increased Output voltage Circuit

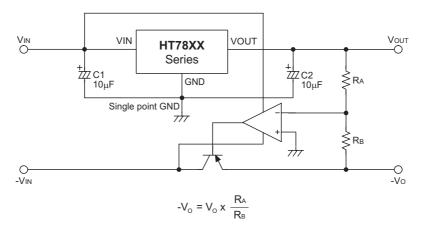


• Dual Supply Circuit

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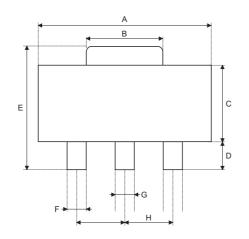
• Tracking Voltage Regulator

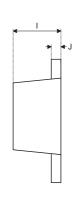




Package Information

3-Pin SOT-89 Outline Dimensions



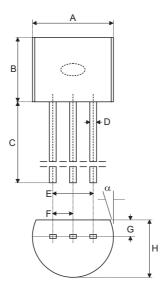


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Cumhal	Dimensions in mil			
Symbol	Min.	Nom.	Max.	
Α	173	_	181	
В	64	_	72	
С	90	_	102	
D	35	_	47	
E	155	_	167	
F	14	_	19	
G	17	_	22	
Н	_	59		
I	55	_	63	
J	14	_	17	



3-Pin TO-92 Outline Dimensions



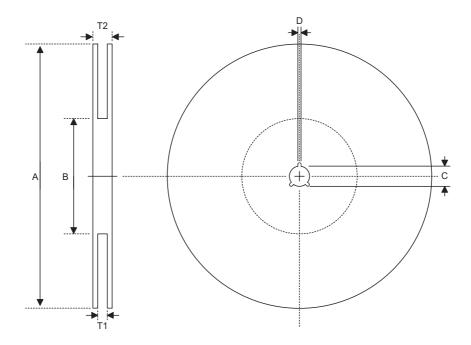
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Sumb al	Dimensions in mil			
Symbol	Min.	Nom.	Max.	
Α	170	_	200	
В	170	_	200	
С	500	_	_	
D	11	_	20	
E	90	_	110	
F	45	_	55	
G	45	_	65	
Н	130	_	160	
I	8	_	18	
α	4°	_	6°	



Product Tape and Reel Specifications

Reel Dimensions

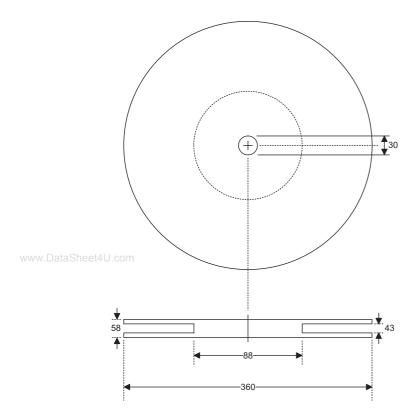


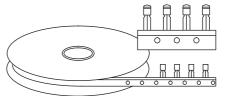
SOT-89

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	180±1.0
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	12.75+0.15
D	Key Slit Width	1.9±0.15
T1	Space Between Flange	12.4+0.2
T2	Reel Thickness	17–0.4

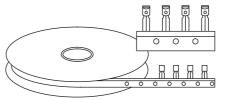


TO-92 Reel Dimensions (Unit: mm)





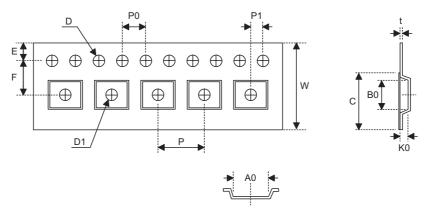
Package Up, Flat Side Up



Package Up, Flat Side Down



Carrier Tape Dimensions



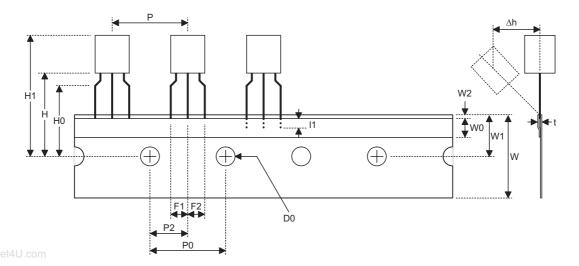
SOT-89

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Symbol	Description	Dimensions in mm
W.com	Carrier Tape Width	12.0+0.3 -0.1
Р	Cavity Pitch	8.0±0.1
Е	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.05
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.10
A0	Cavity Length	4.8±0.1
В0	Cavity Width	4.5±0.1
K0	Cavity Depth	1.8±0.1
t	Carrier Tape Thickness	0.30±0.013
С	Cover Tape Width	9.3



TO-92 Carrier Tape Dimensions



TO-92

Symbol	Description	Dimensions in mm
I1	Taped Lead Length	(2.5)
Р	Component Pitch	12.7±1.0
P ₀	Perforation Pitch	12.7±0.3
P ₂	Component to Perforation (Length Direction)	6.35±0.4
F ₁	Lead Spread	2.5+0.4 -0.1
F ₂	Lead Spread	2.5+0.4 -0.1
Δh	Component Alignment	0±0.1
W	Carrier Tape Width	18.0+1.0 -0.5
W ₀	Hold-down Tape Width	6.0±0.5
W ₁	Perforation Position	9.0±0.5
W ₂	Hold-down Tape Position	(0.5)
H ₀	Lead Clinch Height	16.0±0.5
H ₁	Component Height	Less than 24.7
D ₀	Perforation Diameter	4.0±0.2
t	Taped Lead Thickness	0.7±0.2
Н	Component Base Height	19.0±0.5

Note: Thickness less than 0.38±0.05mm~0.5mm

P0 Accumulated pitch tolerance: ± 1 mm/20pitches.

() Bracketed figures are for consultation only

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